

NCE N-Channel Super Trench II Power MOSFET

Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

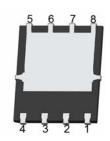
General Features

- V_{DS} =100V,I_D =125A
 - $$\begin{split} R_{DS(ON)} = & 4.0 m\Omega \text{ , typical @ V}_{GS} = & 10 \text{V} \\ R_{DS(ON)} = & 5.0 m\Omega \text{ , typical @ V}_{GS} = & 4.5 \text{V} \end{split}$$
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 150°C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!

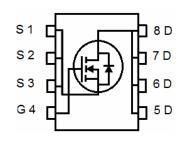
DFN 5X6





Top View

Bottom View



Schematic Diagram

Package Marking and Ordering Information

		•			
Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
P045N10AG	NCEP045N10AG	DFN5X6-8L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	125	А
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	95	Α
Pulsed Drain Current	I _{DM}	500	Α
Maximum Power Dissipation	P _D	150	W
Derating factor		1.2	W/°C
Single pulse avalanche energy (Note 5)	E _{AS}	540	mJ
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	R _{θJC}	0.83	°C/W
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Electrical Characteristics (T_C=25°C unless otherwise noted)

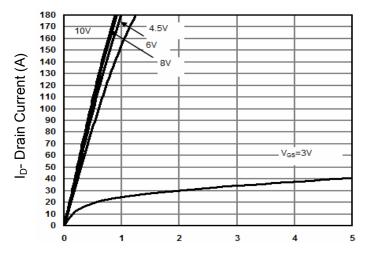
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	100		-	٧
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.2	1.7	2.5	V
Drain Course On Ctate Desistance	Б	V _{GS} =10V, I _D =60A	-	4.0	4.5	- mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =60A		5.0	6.0	
Forward Transconductance	g FS	V_{DS} =5 V , I_{D} =60 A		120	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}	V _{DS} =50V,V _{GS} =0V,	-	6215	-	PF
Output Capacitance	C _{oss}		-	548	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	19	-	PF
Switching Characteristics (Note 4)			•			
Turn-on Delay Time	t _{d(on)}		-	21	-	nS
Turn-on Rise Time	t _r	V_{DD} =50 V , I_D =60 A ,	-	13	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =3 Ω	-	40	-	nS
Turn-Off Fall Time	t _f		-	12	-	nS
Total Gate Charge	Qg	\/ _F0\/ _C0A	-	105	-	nC
Gate-Source Charge	Q _{gs}	V_{DS} =50V, I_{D} =60A,	-	18.4		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	25.5		nC
Drain-Source Diode Characteristics			•		•	
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =60A	-		1.2	٧
Diode Forward Current (Note 2)	Is		-	-	125	Α
Reverse Recovery Time	t _{rr}	$T_J = 25^{\circ}C, I_F = 60A$	-	72	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	140	-	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V $_{\text{DD}}$ =50 V,V $_{\text{G}}$ =10 V,L=0.5 mH,Rg=25 Ω

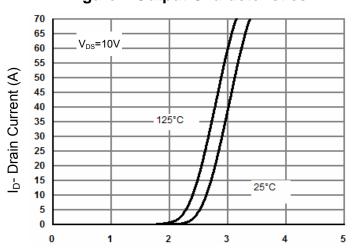


Typical Electrical and Thermal Characteristics



Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

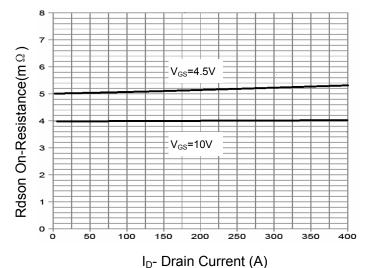


Figure 3 Rdson- Drain Current

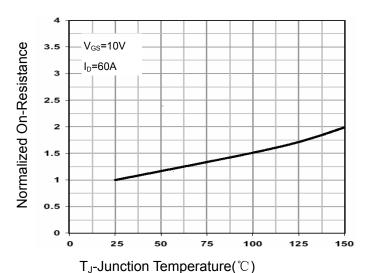
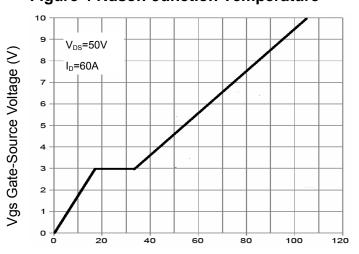
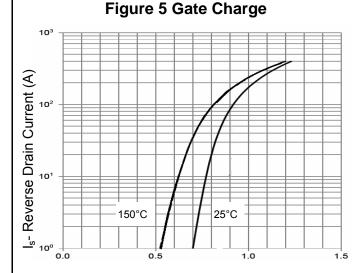


Figure 4 Rdson-Junction Temperature



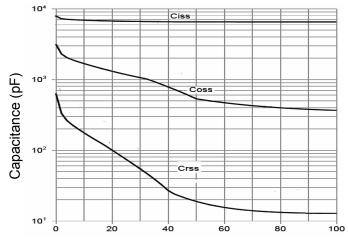
Qg Gate Charge (nC)



Vsd Source-Drain Voltage (V)

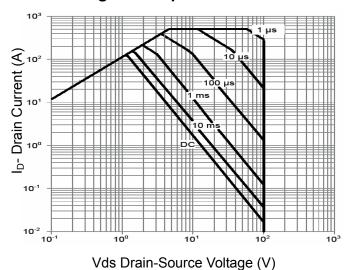
Figure 6 Source- Drain Diode Forward





Vds Drain-Source Voltage (V)

Figure 7 Capacitance vs Vds



- vao Brain Godreo Voltago (V)

Figure 8 Safe Operation Area



T_J-Junction Temperature(°C)

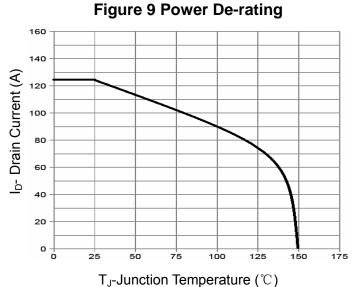


Figure 10 Current De-rating

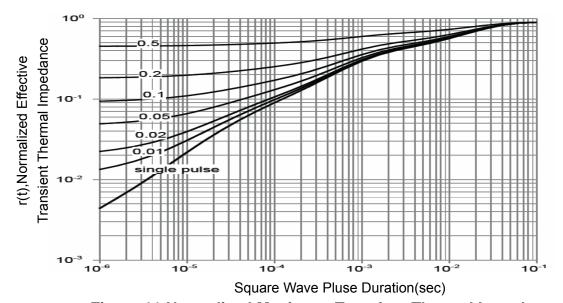
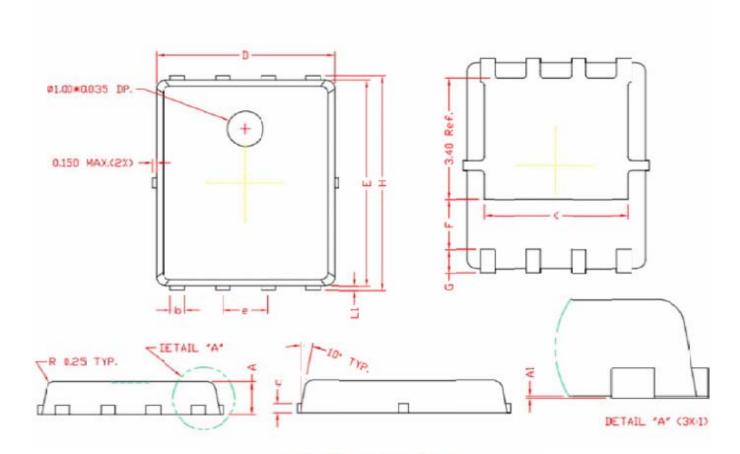


Figure 11 Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX	
A	0.80	0.90	1.00	
A1	0.00	0.03	0.05	
b	0.35 0.42		0.49	
С	0.254 REF.			
D	4.90	5.00	5. 10	
F	1.40 REF.			
E	5.70	5.80	5. 90	
е	1.27 BSC.			
Н	5.95	6.08	6. 20	
L1	0.10	0.14	0.18	
G	0.60 REF. 4.00 REF.			
K				

NCEP045N10AG



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